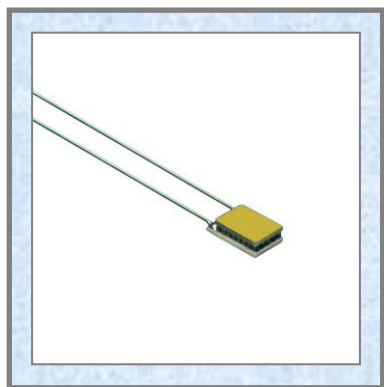


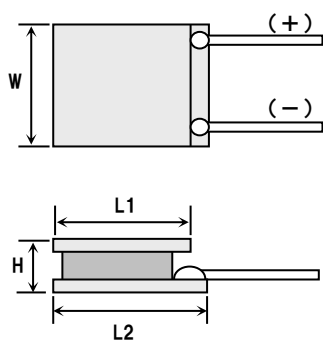
THERMO MODULE DATA

Model **KSMH023** (**RoHS 2002/95/EC Compliant**)



Th	$\Delta T_{max}(^{\circ}C)$	I _{max} (A)	V _{max} (v)	Q _{cmax} (w)
27°C	75	2.0	2.7	3.3
70°C	93	2.0	3.4	3.6

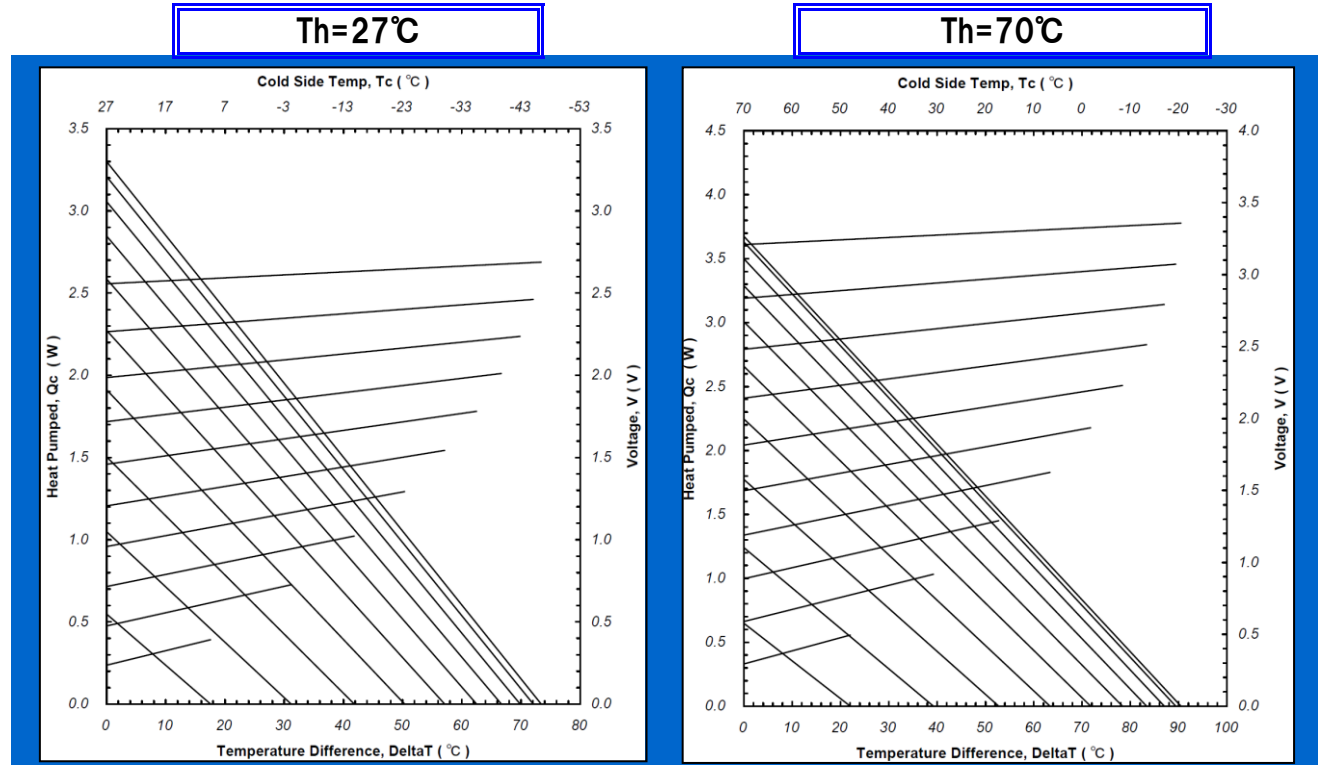
	W	L1	L2	H
Size(mm)	6.0	8.2	8.2	1.65
Tolerance(mm)	±0.2	±0.2	±0.2	±0.1
Metallization	Cu-Ni-Au			
Ceramic material	Alumina			
Assembly solder	SnSb (melting point:232°C)			



Option

Assembly solder	AuSn (melting point:280°C)
Ceramic material	All models can be assembled with alumina &/or aluminum nitride ceramics.
Pretinning solder	InSn (melting point:117°C), BiSn (melting point:138°C), SnAgCu (melting point:217°C) is also available, when AuSn is selected for assembly solder.

Performance Diagram



Ambient	Nitrogen
Current value	I = 0.2 – 2.0 A (Step = 0.20 A)

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